

2SK1216

Silicon N Channel Junction Type

For video camera initial stage amplification

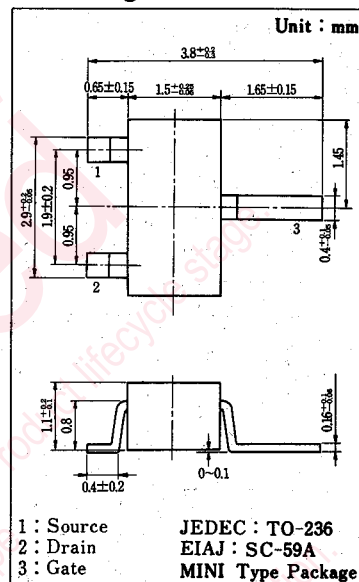
■ Features

- Low small-signal short-circuit input capacitance C_{iss}
- High mutual conductance g_m
- A MINI type package that allows downsizing of equipment and automatic insertion by taping and magazine packaging

■ Absolute Maximum Ratings ($T_a=25^\circ\text{C}$)

Item	Symbol	Value	Unit
Gate-Drain Voltage	V_{GDO}	-10	V
Gate-Source Voltage	V_{SGO}	10	V
Drain Current	I_D	50	mA
Gate Current	I_G	5	mA
Power Dissipation	P_D	200	mW
Channel Temperature	T_{ch}	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 ~ +150	$^\circ\text{C}$

■ Package Dimensions

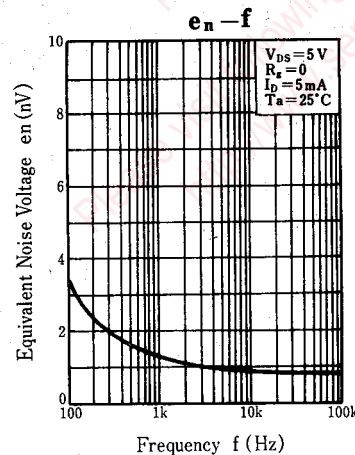
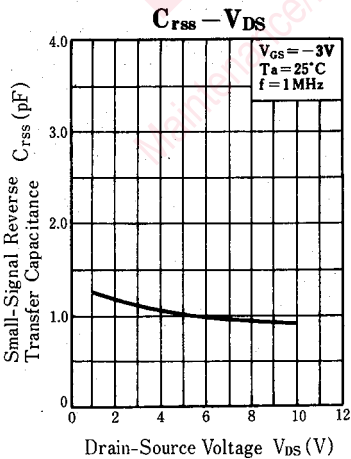
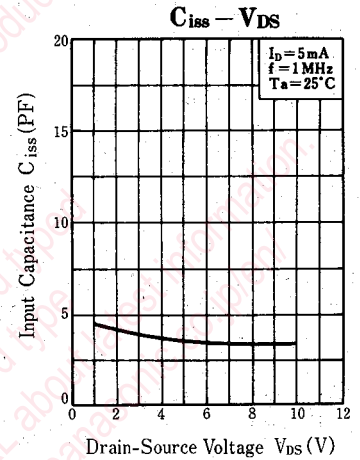
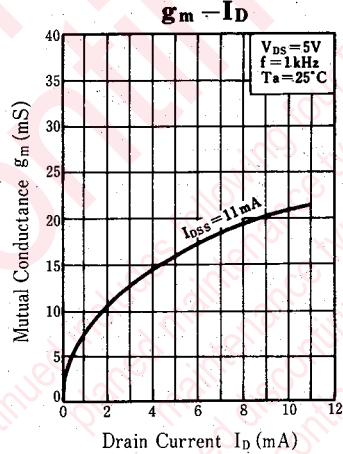
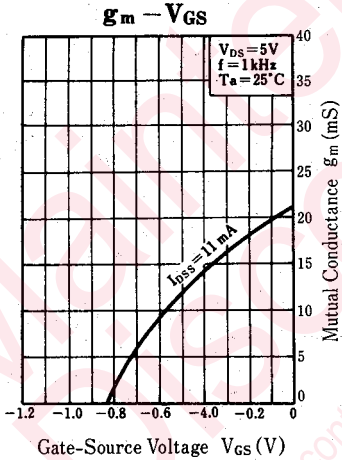
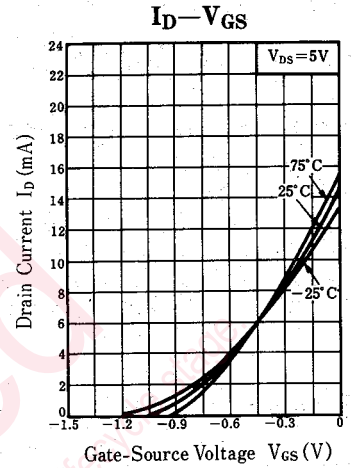
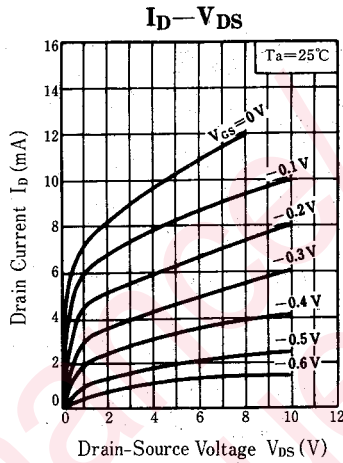
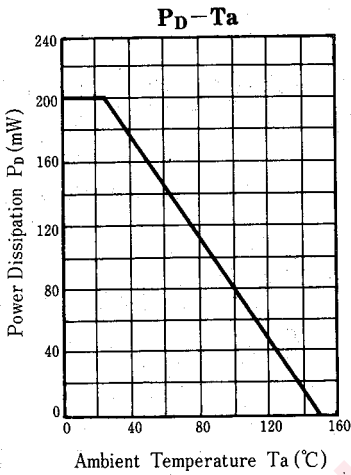


■ Electrical Characteristics ($T_a=25^\circ\text{C}$)

Item	Symbol	Condition	min.	typ.	max.	Unit
Gate-Drain Voltage	V_{GDO}	$I_G = -100 \mu\text{A}$	10			V
Gate-Source Voltage	V_{GSO}	$I_G = -100 \mu\text{A}$	10			V
Gate Cutoff Current	I_{GSS}	$V_{GS} = -7 \text{ V}, V_{DS} = 0$			-2	nA
Drain Current	I_{DSS}	$V_{DS} = 5 \text{ V}, V_{GS} = 0$	9.2		14.0	mA
Gate-Source Cutoff Voltage	V_{GSC}	$V_{DS} = 5 \text{ V}, I_D = 100 \mu\text{A}$			-3	V
Mutual Conductance	g_m	$V_{DS} = 5 \text{ V}, V_{GS} = 0, f = 1 \text{ kHz}$	20	22		mS
Input Capacitance	C_{iss}	$V_{DS} = 5 \text{ V}, I_D = 5 \text{ mA}, f = 1 \text{ MHz}$		3.9	4.0	pF

■ Type Name Marking





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